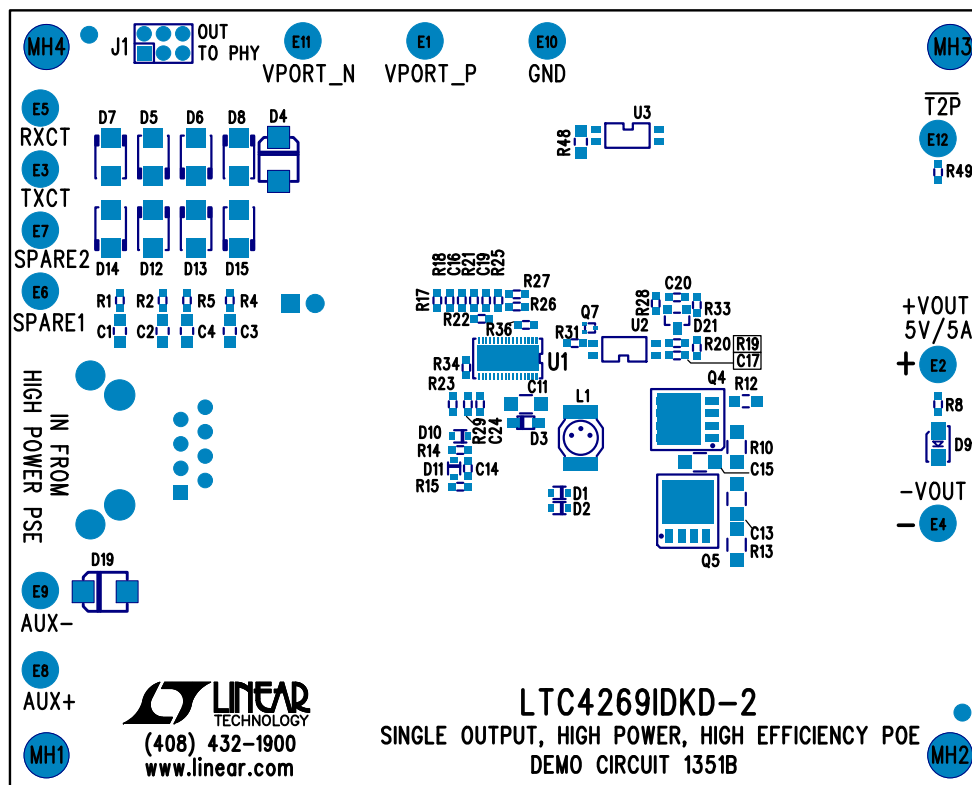
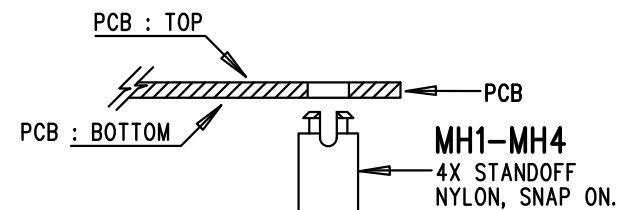



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	REBUILD WITH CHANGE	RYAN H.	03-16-12



## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AND SMA CONNECTORS AS SHOWN BELOW:



APPROVALS		 <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>	
PCB DES.	KIM T.		
APP ENG.	RYAN H.	TITLE: TOP ASSEMBLY DRAWING	
		SINGLE OUTPUT, HIGH POWER, HIGH EFFICIENCY POE	
		SIZE N/A	IC NO. LTC4269IDKD-2 DEMO CIRCUIT 1351B
			REV. 1
SCALE = NONE		FILENAME: DC1351B-1.PCB	SHT 1 OF 2